

General Description

The WSD3039DN56 uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.

The WSD3039DN56 meet the RoHS and Green Product requirement, 100% E_{AS} guaranteed with full function reliability approved.

Features

- Advanced high cell density Trench technology
- Super Low Gate Charge
- 100% E_{AS} Guaranteed
- Green Device Available

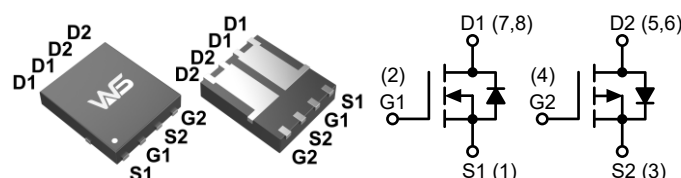
Product Summary

| BV_{DSS} | $R_{DS(ON)}$ | I_D |
|------------|--------------|-------|
| 30V | 14m Ω | 20A |
| -30V | 24m Ω | -16A |

Applications

- Wireless charging
- Boost driver
- Brushless motor

DFN5X6-8L Pin Configuration



Absolute Maximum Ratings ($T_C=25^{\circ}\text{C}$, Unless Otherwise Noted)

| Symbol | Parameter | Rating | | Units |
|-------------------------------|---|------------|------------|--------------------|
| | | N-Channel | P-Channel | |
| V_{DS} | Drain-Source Voltage | 30 | -30 | V |
| V_{GS} | Gate-Source Voltage | ± 20 | ± 20 | V |
| $I_D@T_C=25^{\circ}\text{C}$ | Continuous Drain Current, $V_{GS} @ 10\text{V}^1$ | 20 | -16 | A |
| $I_D@T_A=100^{\circ}\text{C}$ | Continuous Drain Current, $V_{GS} @ 10\text{V}^1$ | 10 | -8 | |
| I_{DM} | Pulsed Drain Current ² | 52 | -45 | |
| E_{AS} | Single Pulse Avalanche Energy ³ | 22 | 45 | mJ |
| I_{AS} | Avalanche Current | 21 | -30 | A |
| $P_D@T_A=25^{\circ}\text{C}$ | Power Dissipation ⁴ | 18 | 18 | W |
| T_{STG} | Storage Temperature Range | -55 to 150 | -55 to 150 | $^{\circ}\text{C}$ |
| T_J | Operating Junction Temperature Range | -55 to 150 | -55 to 150 | |

Thermal Data

| Symbol | Parameter | Typ. | Max. | Units |
|-----------------|---|------|------|-----------------------------|
| $R_{\theta JA}$ | Thermal Resistance, Junction-to-Ambient ¹ | --- | 55 | $^{\circ}\text{C}/\text{W}$ |
| $R_{\theta JC}$ | Thermal Resistance, Junction-to-Case ¹ , ($t \leq 10\text{sec}$) | --- | 5 | |

N-Channel Electrical Characteristics ($T_J=25^{\circ}\text{C}$, Unless Otherwise Noted)

| Symbol | Parameter | Conditions | Min. | Typ. | Max. | Units |
|--------------|--|---|------|------|-----------|------------|
| BV_{DSS} | Drain-Source Breakdown Voltage | $V_{GS}=0V$, $I_D=250\mu A$ | 30 | --- | --- | V |
| $R_{DS(ON)}$ | Static Drain-Source On-Resistance ² | $V_{GS}=10V$, $I_D=10A$ | --- | 14 | 23 | m Ω |
| | | $V_{GS}=4.5V$, $I_D=5A$ | --- | 19 | 28 | |
| $V_{GS(th)}$ | Gate Threshold Voltage | $V_{GS}=V_{DS}$, $I_D=250\mu A$ | 1.0 | 1.6 | 2.5 | V |
| I_{DSS} | Drain-Source Leakage Current | $V_{DS}=24V$, $V_{GS}=0V$, $T_J=25^{\circ}\text{C}$ | --- | --- | 1.0 | μA |
| | | $V_{DS}=24V$, $V_{GS}=0V$, $T_J=55^{\circ}\text{C}$ | --- | --- | 5.0 | |
| I_{GSS} | Gate-Source Leakage Current | $V_{GS}=\pm 20V$, $V_{DS}=0V$ | --- | --- | ± 100 | nA |
| g_{fs} | Forward Transconductance | $V_{DS}=5V$, $I_D=10A$ | --- | 16 | --- | S |
| R_g | Gate Resistance | $V_{DS}=0V$, $V_{GS}=0V$, $f=1.0\text{MHz}$ | --- | 2.5 | 5 | Ω |
| Q_g | Total Gate Charge (4.5V) | $V_{DS}=20V$, $V_{GS}=4.5V$, $I_D=10A$ | --- | 7.2 | --- | nC |
| Q_{gs} | Gate-Source Charge | | --- | 1.4 | --- | |
| Q_{gd} | Gate-Drain Charge | | --- | 2.2 | --- | |
| $T_{d(on)}$ | Turn-On Delay Time | $V_{DD}=15V$, $V_{GS}=10V$, $R_G=3.3\Omega$, $I_D=5A$ | --- | 4.1 | --- | ns |
| T_r | Rise Time | | --- | 9.8 | --- | |
| $T_{d(off)}$ | Turn-Off Delay Time | | --- | 15.5 | --- | |
| T_f | Fall Time | | --- | 6.0 | --- | |
| C_{iss} | Input Capacitance | $V_{DS}=15V$, $V_{GS}=0V$, $f=1.0\text{MHz}$ | --- | 572 | --- | pF |
| C_{oss} | Output Capacitance | | --- | 81 | --- | |
| C_{rss} | Reverse Transfer Capacitance | | --- | 65 | --- | |

Diode Characteristics

| Symbol | Parameter | Conditions | Min. | Typ. | Max. | Units |
|----------|--|---|------|------|------|-------|
| I_S | Continuous Source Current ^{1,5} | $V_G=V_D=0V$, Force Current | --- | --- | 10 | A |
| V_{SD} | Diode Forward Voltage ² | $V_{GS}=0V$, $I_S=1A$, $T_J=25^{\circ}\text{C}$ | --- | --- | 1.2 | V |

Note:

1. The data tested by surface mounted on a 1 inch² FR-4 board with 20Z copper.
2. The data tested by pulsed , pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$
3. The E_{AS} data shows Max. rating . The test condition is $V_{DD}=25V$, $V_{GS}=10V$, $L=0.1\text{mH}$, $I_{AS}=10A$
4. The power dissipation is limited by 150°C junction temperature.
5. The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation.

P-Channel Electrical Characteristics ($T_J=25^{\circ}\text{C}$, Unless Otherwise Noted)

| Symbol | Parameter | Conditions | Min. | Typ. | Max. | Units |
|--------------|--|--|------|------|-----------|------------|
| BV_{DS} | Drain-Source Breakdown Voltage | $V_{GS}=0V$, $I_D=-250\mu A$ | -30 | --- | --- | V |
| $R_{DS(ON)}$ | Static Drain-Source On-Resistance ² | $V_{GS}=-10V$, $I_D=-7A$ | --- | 24 | 31 | m Ω |
| | | $V_{GS}=-4.5V$, $I_D=-5A$ | --- | 36 | 52 | |
| $V_{GS(th)}$ | Gate Threshold Voltage | $V_{GS}=V_{DS}$, $I_D=-250\mu A$ | -1.0 | --- | -2.5 | V |
| I_{DSS} | Drain-Source Leakage Current | $V_{DS}=-24V$, $V_{GS}=0V$, $T_J=25^{\circ}\text{C}$ | --- | --- | 1.0 | μA |
| | | $V_{DS}=-24V$, $V_{GS}=0V$, $T_J=55^{\circ}\text{C}$ | --- | --- | 5.0 | |
| I_{GSS} | Gate-Source Leakage Current | $V_{GS}=\pm 20V$, $V_{DS}=0V$ | --- | --- | ± 100 | nA |
| g_{fs} | Forward Transconductance | $V_{DS}=-5V$, $I_D=-7A$ | --- | 15 | --- | S |
| R_g | Gate Resistance | $V_{DS}=0V$, $V_{GS}=0V$, $f = 1.0\text{MHz}$ | --- | 15 | 30 | Ω |
| Q_g | Total Gate Charge (-4.5V) | $V_{DS}=-20V$, $V_{GS}=-4.5V$, $I_D=-7A$ | --- | 9.8 | --- | nC |
| Q_{gs} | Gate-Source Charge | | --- | 2.2 | --- | |
| Q_{gd} | Gate-Drain Charge | | --- | 3.4 | --- | |
| $T_{d(on)}$ | Turn-On Delay Time | $V_{DD}=-15V$, $V_{GS}=-10V$, $R_G=3.3\Omega$, $I_D=-5A$ | --- | 16.4 | --- | ns |
| T_r | Rise Time | | --- | 20.2 | --- | |
| $T_{d(off)}$ | Turn-Off Delay Time | | --- | 55 | --- | |
| T_f | Fall Time | | --- | 10 | --- | |
| C_{iss} | Input Capacitance | $V_{DS}=-15V$, $V_{GS}=0V$, $f = 1.0\text{MHz}$ | --- | 930 | --- | pF |
| C_{oss} | Output Capacitance | | --- | 148 | --- | |
| C_{rss} | Reverse Transfer Capacitance | | --- | 115 | --- | |

Diode Characteristics

| Symbol | Parameter | Conditions | Min. | Typ. | Max. | Units |
|----------|--|--|------|------|------|-------|
| I_S | Continuous Source Current ^{1,5} | $V_G=V_D=0V$, Force Current | --- | --- | -8 | A |
| V_{SD} | Diode Forward Voltage ² | $V_{GS}=0V$, $I_S=-1A$, $T_J=25^{\circ}\text{C}$ | --- | --- | -1.2 | V |

Note:

1. The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
2. The data tested by pulsed , pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$
3. The E_{AS} data shows Max. rating . The test condition is $V_{DD}=-25V$, $V_{GS}=-10V$, $L=0.1mH$, $I_{AS}=-10A$
4. The power dissipation is limited by 150°C junction temperature.
5. The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation.

N-Channel Typical Characteristics

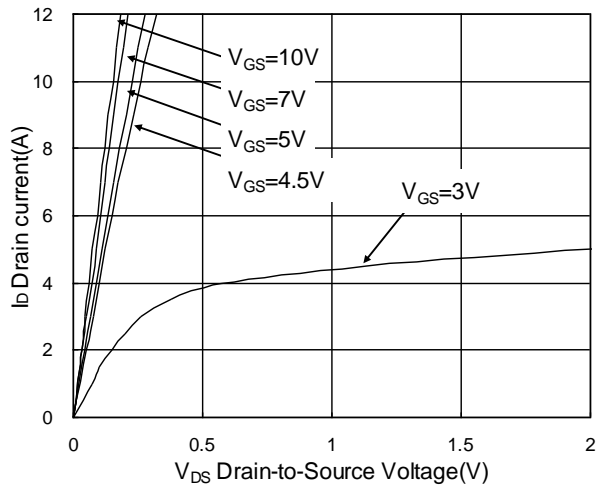


Fig.1 Typical Output Characteristics

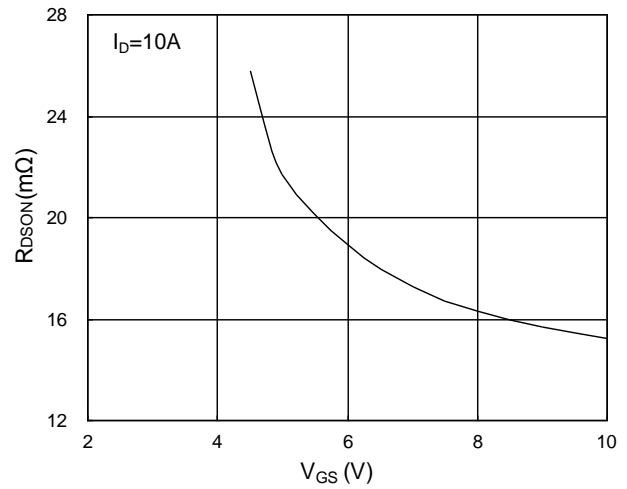


Fig.2 On-Resistance v.s Gate-Source

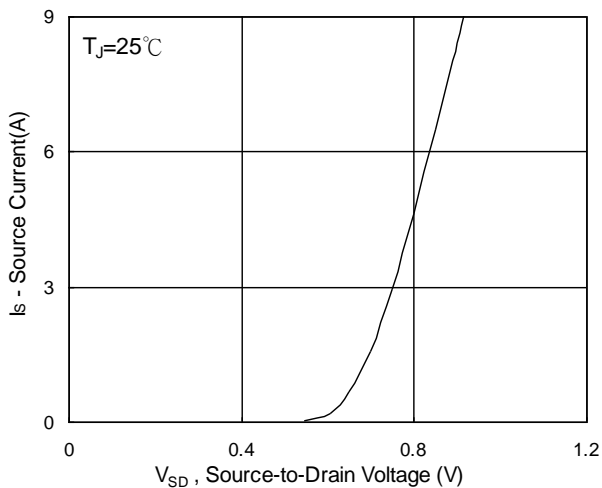


Fig.3 Forward Characteristics Of Reverse

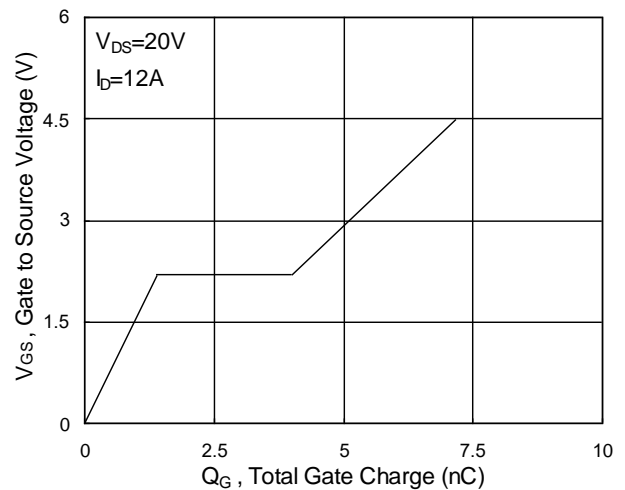


Fig.4 Gate-Charge characteristics

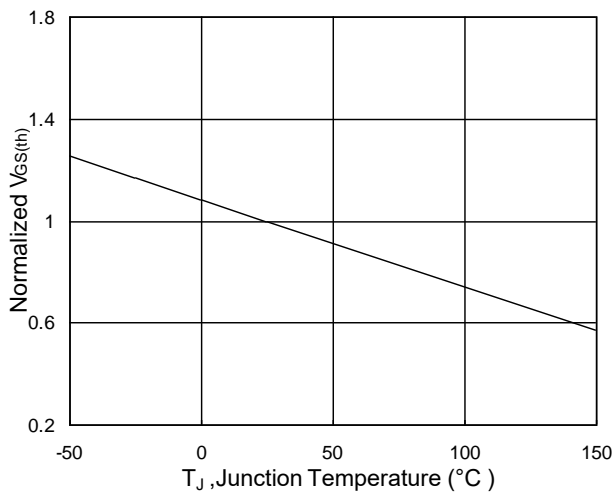


Fig.5 Normalized $V_{GS(th)}$ v.s T_J

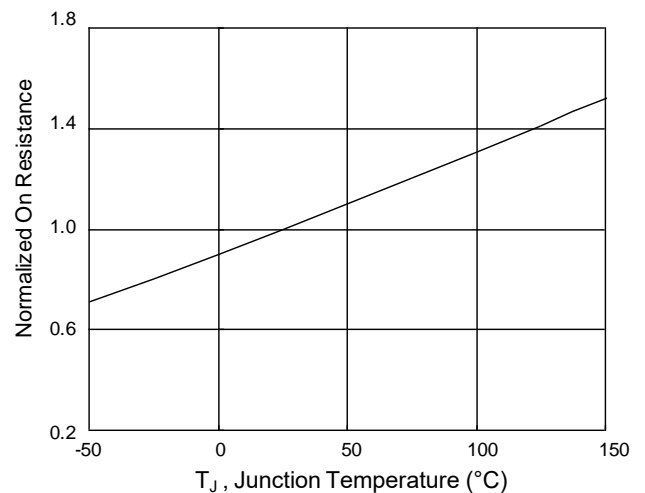
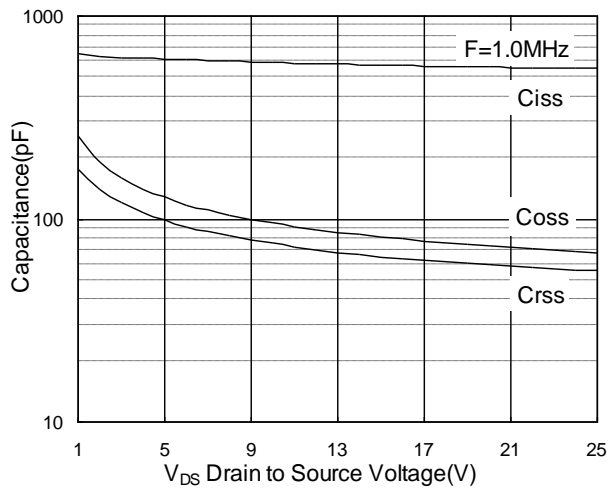
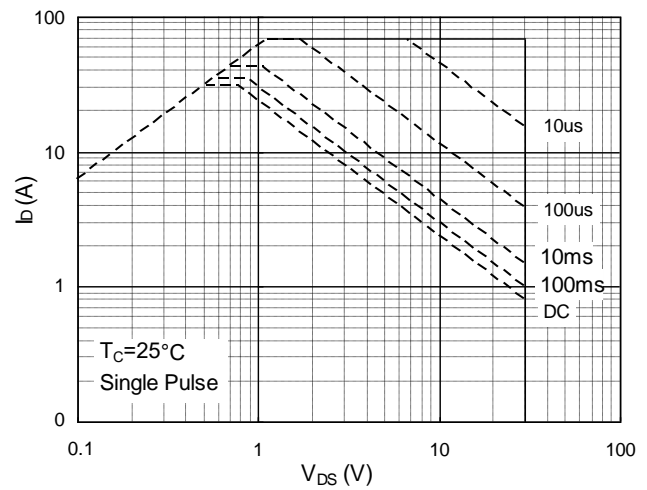
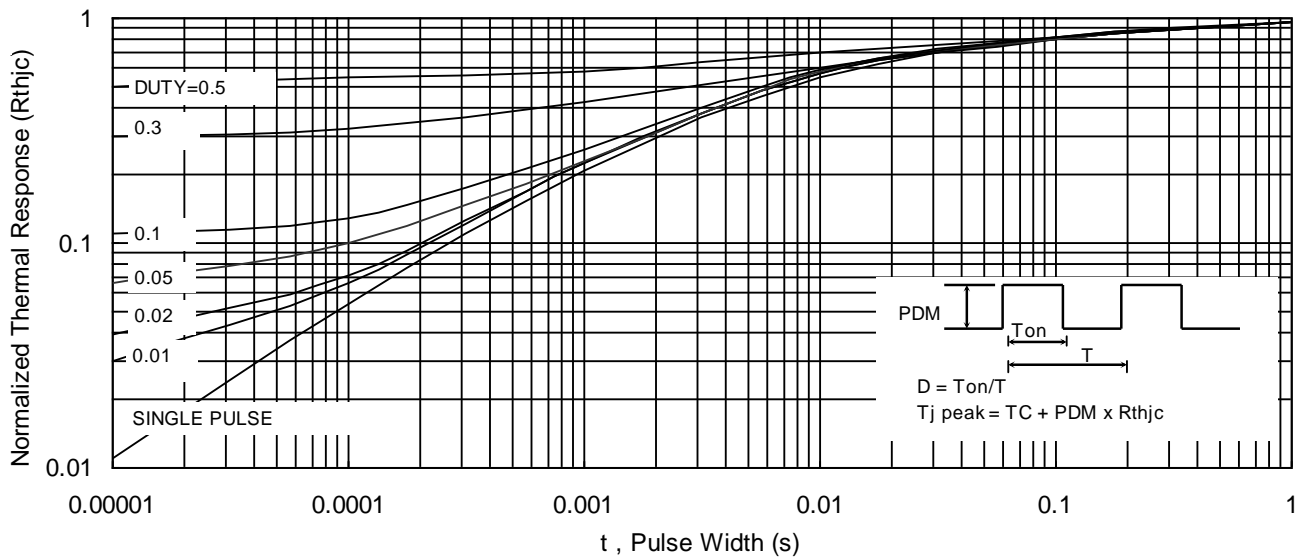
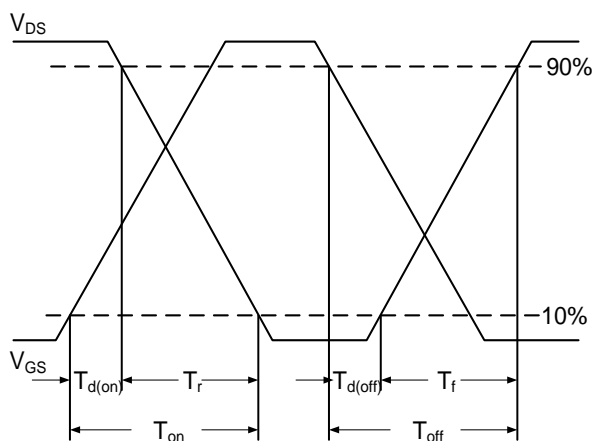
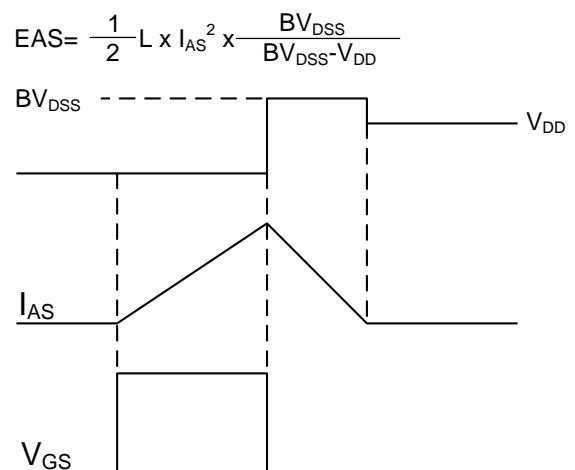


Fig.6 Normalized $R_{DS(on)}$ v.s T_J

N-Channel Typical Characteristics (Cont.)

Fig.7 Capacitance

Fig.8 Safe Operating Area

Fig.9 Normalized Maximum Transient Thermal Impedance

Fig.10 Switching Time Waveform

Fig.11 Unclamped Inductive Waveform

P-Channel Typical Characteristics

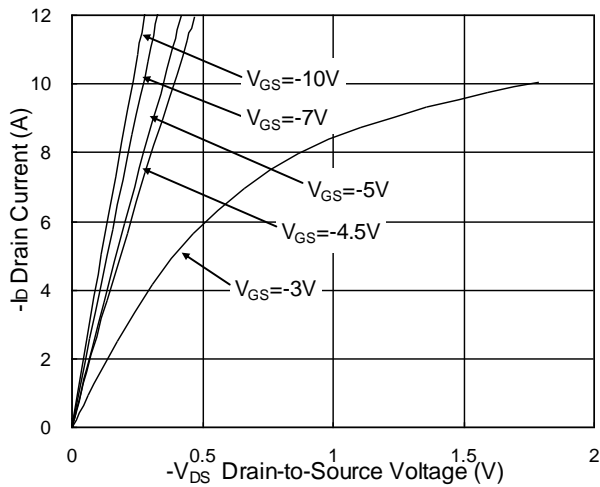


Fig.1 Typical Output Characteristics

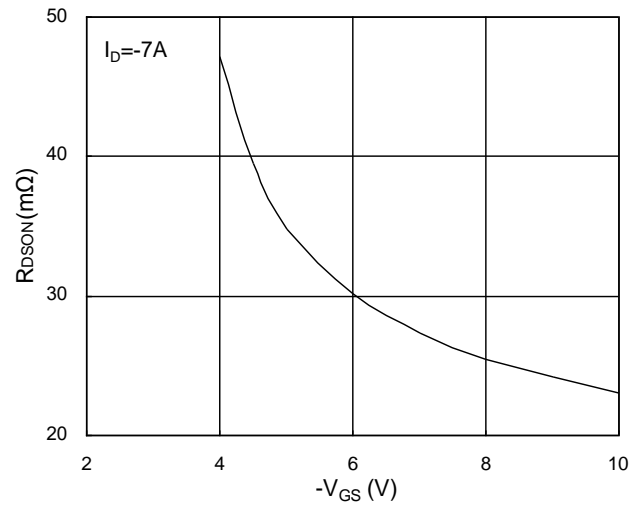


Fig.2 On-Resistance v.s Gate-Source

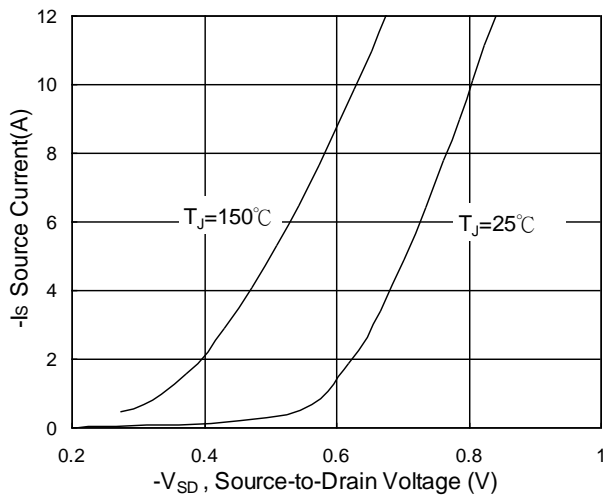


Fig.3 Forward Characteristics Of Reverse

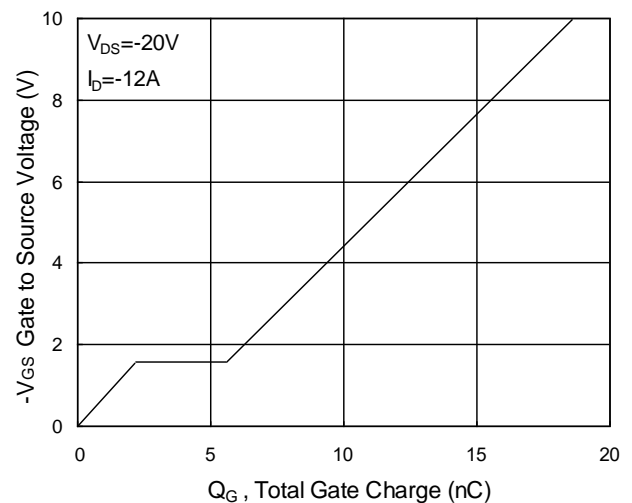


Fig.4 Gate-Charge Characteristics

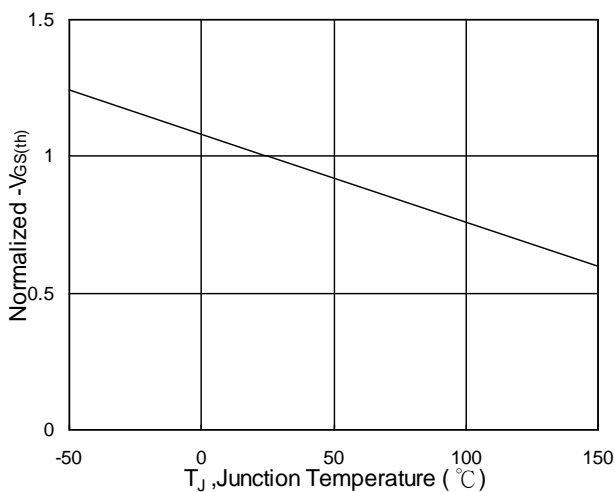


Fig.5 Normalized $V_{GS(th)}$ v.s T_J

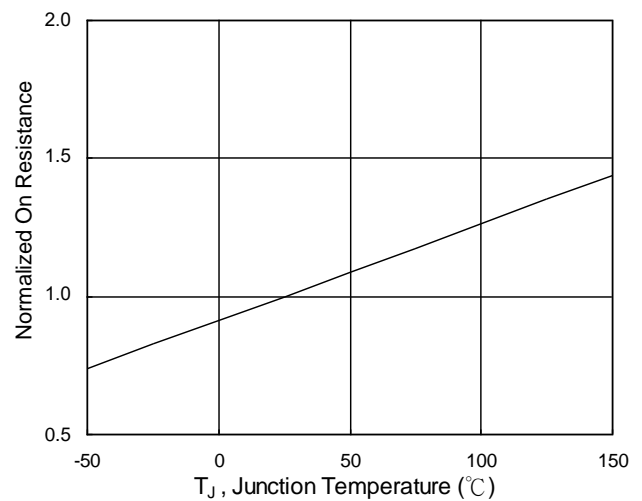
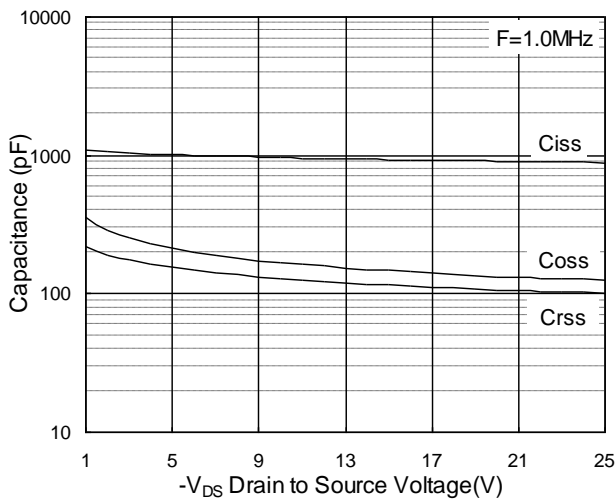
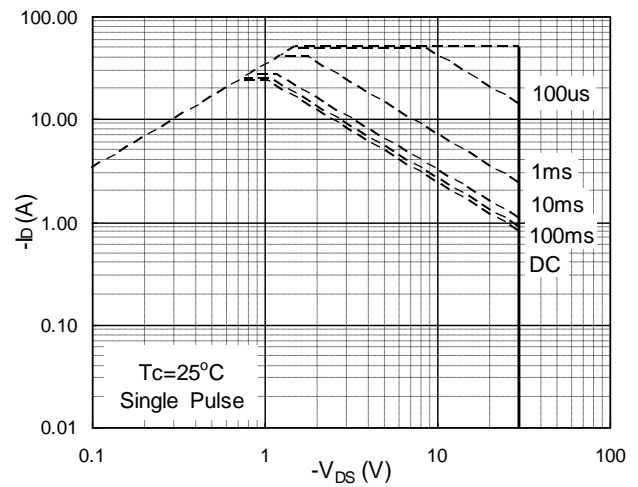
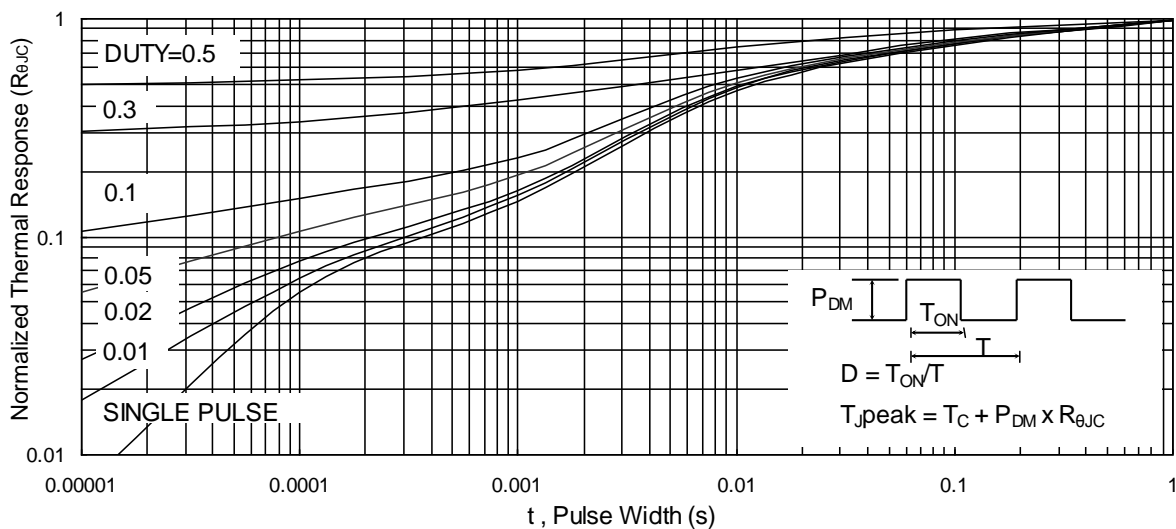
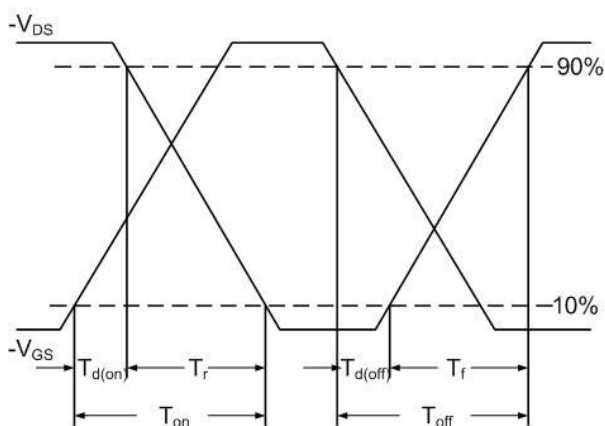
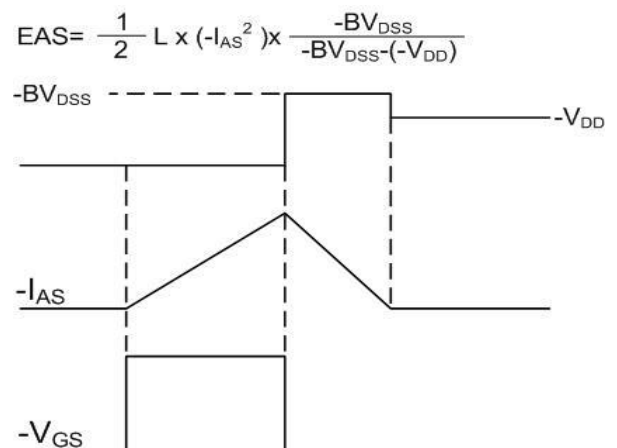
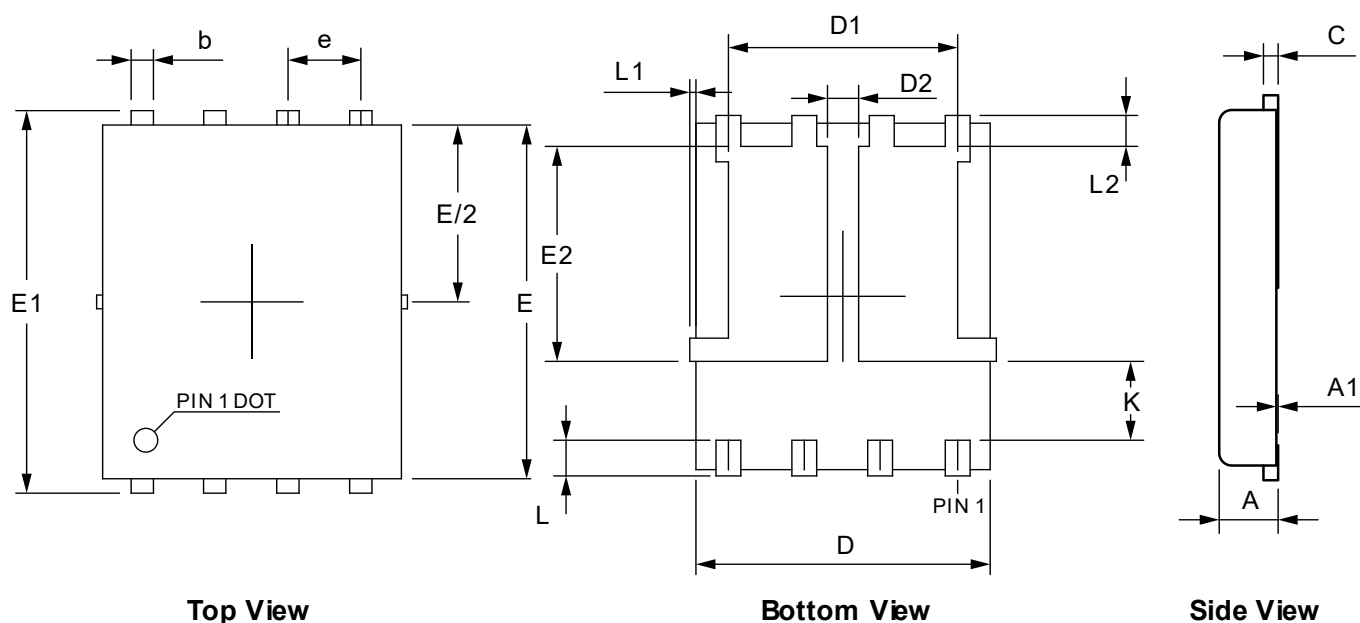


Fig.6 Normalized $R_{DS(on)}$ v.s T_J

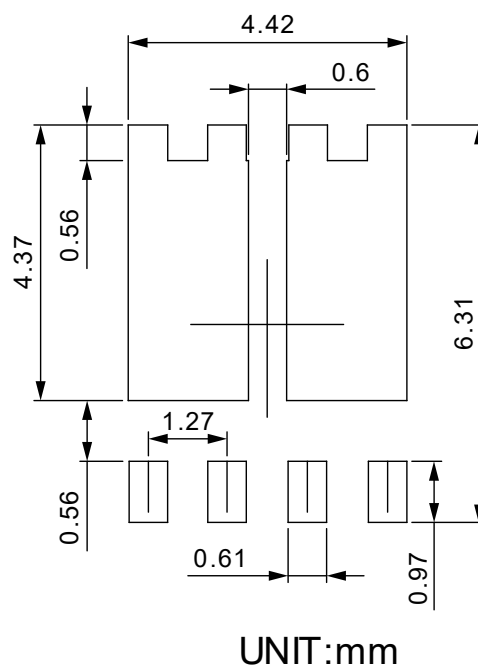
P-Channel Typical Characteristics (Cont.)

Fig.7 Capacitance

Fig.8 Safe Operating Area

Fig.9 Normalized Maximum Transient Thermal Impedance

Fig.10 Switching Time Waveform

Fig.11 Unclamped Inductive Waveform

Packaging information



| SYMBOL | MILLIMETERS | | INCHES | |
|--------|-------------|-------|-----------|-------|
| | MIN. | MAX. | MIN. | MAX. |
| A | 0.900 | 1.200 | 0.035 | 0.047 |
| A1 | 0.000 | 0.050 | 0.000 | 0.002 |
| b | 0.300 | 0.500 | 0.012 | 0.020 |
| c | 0.150 | 0.300 | 0.006 | 0.012 |
| D | 4.800 | 5.000 | 0.189 | 0.197 |
| D1 | 3.550 | 4.550 | 0.140 | 0.179 |
| D2 | 0.500 | 0.910 | 0.020 | 0.036 |
| E | 5.650 | 5.850 | 0.222 | 0.230 |
| E1 | 5.900 | 6.200 | 0.232 | 0.244 |
| E2 | 3.200 | 3.780 | 0.126 | 0.149 |
| e | 1.27 BSC | | 0.050 BSC | |
| K | 1.100 | - | 0.043 | - |
| L | 0.500 | 0.800 | 0.020 | 0.031 |
| L1 | 0.000 | 0.150 | 0.000 | 0.006 |
| L2 | 0.325 | 0.610 | 0.013 | 0.024 |

RECOMMENDED LAND PATTERN



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